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Applicant:  
David Muradian et al.

(Use several sheets if necessary)

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U.S. Patent Documents

Init.		Document No.	Date	Name	Class	Subclass	Filing Date
EP	1	5,267,017	11/30/1993	Uritsky et al.	356	375	05/20/1992
EP	2	5,539,752	07/23/1996	Berezin et al.	371	22/1	06/30/1995
EP	3	5,777,901	07/07/1998	Berezin et al.	364	578	09/29/1995
EP	4	5,870,187	02/09/1999	Uritsky et al.	356	237	08/08/1997
EP	5	6,035,244	03/07/2000	Chen et al.	700	110	10/22/1997

Foreign Documents

Translation

Init.		Document No.	Date	Country	Class	Subclass	Yes	No
EP	6	EP 0 641 020 A2 & A3	03/01/1995 07/26/1995	Europe	H01L	21/66		

Other Documents (Including Author, Title, Date, Pertinent Pages, etc.)

EP	7	J. Segal et al, "Determining Redundancy Requirements for Memory Arrays with Critical Area Analysis", <u>Proceedings of the 1999 IEEE International Workshop on Memory Technology, Design, and Testing</u> , IEEE Comput. Soc., August 1999.
EP	8	J. Segal et al., " A Framework for Extracting Defect Density Information for Yield Modeling from In-line Defect Inspection for Real-time Prediction of Random Defect Limited Yields", <u>Proceedings of the 1999 IEEE International Symposium on Semiconductor Manufacturing</u> , (Piscataway, NJ: Institute of Electrical and Electronics Engineers), pp. 403-406. 1999 (no month)
EP	9	J. Segal, et al, "Predicting Failing Bitmap Signatures for Memory Arrays with Critical Area Analysis", <u>1999 Proceedings IEEE/SEMI Advanced Semiconductor Manufacturing Conference and Workshop (ASMC)</u> , p. 178-182, 1999.

Examiner *Evan Pert*

Date Considered *8-18-03*

Examiner: Initial if citation considered, whether or not citation is in conference with MPEP 609; Draw line through citation if not conformance and not considered. Include a copy of this form with the next communication to applicant.